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RoHS, ELV適合品
RoHS, ELV COMPLIANT

Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.

1. リフロー回数: 2回。但し、2回目のリフローにおいては、一度、室温に戻すこと。

Note2. The temperature indicates the board surface temperature on the connector lead area.

2. リフロー温度の測定は、コネクタリード部の基板表面温度を測定のこと。

Note3. Hand soldering: 280~300℃, 2s max.

3. 手半田温度: 280~300℃, 2S以内

Note4. Coplanarity: 0.1 max.

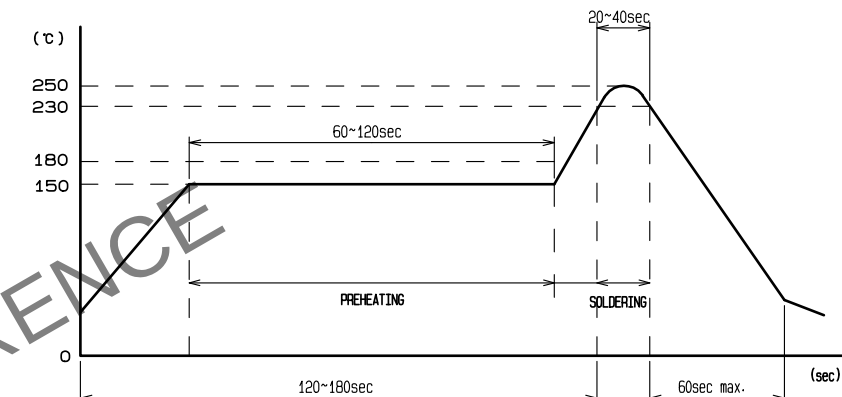
4. 端子平坦度: 0.1以下

Note5. Recommended thickness of PCB: 1.6mm

5. 推奨基板厚: 1.6mm

RECOMMENDED REFLOW PROFILE

IR reflow condition	IR リフロー条件
Preheating area 150℃ for 60 to 120 seconds	予熱加熱: 60~120秒, 150℃
Peak temperature: 230℃	ピーク温度: 230℃
Soldering area 230±15℃ or 10 seconds max.	リフロー温度: 230~240℃, 10秒以内
230℃ min. for 10 30 seconds	230℃以上: 10~30秒



スタンドオフ STANDS OFF

嵌合状態図
Mated connectors

パネル寸法図
Pannel layout

2	PPS	BROWN	5	PS	TRAY NATURAL
1	COPPER ALLOY	TIN PLATING	4	BRASS	TIN PLATING
			3	BRASS	TIN PLATING
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
					CHECKED
					DATE
APPROVED : KI. HIROKAWA 20200331			DRAWING NO. EDC-166859-55-00		
CHECKED : EJ. WAKATSUKI 20200327			PART NO. GT17HN-16DP-2H(55)		
DESIGNED : TS. KUBOTA 20200325			CODE NO. CL767-0153-7-55		
DRAWN : YK. MITSUISHI 20200313					

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